



Product Change Notification

Change Notification #: 118764-00
Change Title: Microprocessor land-grid array (LGA) products sold in trays
Transport Media: Adding a moisture-barrier bag, 2 desiccant pouches, and a humidity-indicator card
Date of Publication: March 4, 2022

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	May 09, 2022
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Description of Change:

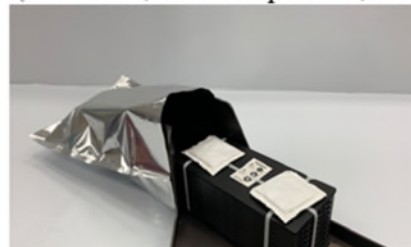
Intel is changing the packaging materials for Intel microprocessor land-grid array (LGA) products sold in trays. This change will not affect packaging for products sold in retail boxes. Intel will package these LGA microprocessors in a moisture-barrier bag (MBB) sealed with two desiccant pouches and a humidity-indicator card (HIC). Standard Intel product-and-handling labels will be affixed to the outside of the MBB.

PICTORAL EXAMPLES

Current Tray Packaging Configuration
(No MBB, desiccant pouches, or HIC)



New Tray Packaging Configuration
(with MBB, desiccant pouches, and HIC)



Standard Intermediate Box (I-box) Label will be placed on the MBB.	Standard MBB Handling Label will be placed on MBB.
 The image shows an Intel Intermediate Box (I-box) label. It includes fields for (P) CUST PROD, (V) SUPPLIER (04195 INTEL), (1B) BOX (RLP00008), (1P) IPN (INTEL PRODUCT NAMEXX), (S) SPEC (S 1234), (3BP) MFR (123456), (1T) LOT (FPO NUMBER), (Q) QTY (12345), and (SD) DATE (YYMM). It also features a LEVEL 1 label with a BAG SEAL DATE (08DEC09) and a vertical stamp 'ASSEMBLED IN MALAYSIA'.	 The image shows an Intel MBB Handling Label. It features a 'Caution' warning with a moisture-sensitive symbol and the text 'This bag contains MOISTURE-SENSITIVE DEVICES'. It includes a LEVEL (MSL) field and a list of instructions: 1. Calculated shelf life in sealed bag: 12 months at < 40 °C and < 90% relative humidity (RH); 2. Peak package body temperature; 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be: a) Mounted within: hours of factory conditions < 30°C/60% RH, or b) Stored per J-STD-033; 4. Devices require bake, before mounting, if: a) Humidity Indicator Card reads >10% for level 2a - 5a, devices or >60% for level 2 devices when read at 23 ± 5 °C b) 3a or 3b are not met; 5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure. A note at the bottom states: Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J-STD-020. The label is identified as J-STD-033D-3-4A.

Note: All images above are for example only. Any custom-specific labels will be placed on the MBB in like manner.

Customer Impact of Change and Recommended Action:

Migration to the new packaging will start May 9, 2022, and continue through the end of 2022. During that time, customers may receive LGA microprocessors in both the old and new packaging. Customers may need to make changes to their processes, such as removing the LGA microprocessors from the MBB and disposing of MBBs, the HICs, and the desiccant pouches. This change does not affect product shelf life or moisture-sensitivity level. Nor does the change require the products to be re-qualified or re-certified.

Intel is making this packaging change to reduce product exposure to things such as water, ambient moisture, or contaminants during shipment and storage. Such exposure could lead to the discoloration of the product or other undesired effects. This packaging change will enhance product-quality control after manufacturing and help customers limit the products' exposure to environmental factors.

Please contact your local Intel representative for any questions or concerns regarding the change communicated within this Product Change Notification.

Products Affected/Intel Ordering Codes:

Please see the attached Excel spreadsheet with the list of affected products.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 4, 2022	00	Originally Published PCN



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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

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